

### **Features**

- 6868 UV LED
- ALN substrate with anti-UV Glasses Lens
- ROHS and REACH Compliant
- MSL 4 qualified according to J-STD 020
- ESD 8KV

## **Applications**

- UV Curing
- Medical applications
- Counterfeit Detection
- Purification

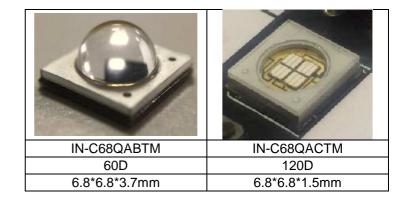
## **Description**

The IN-C68QA(X)TM UV series is a high-power(10W)

UV LED with Good Thermal Dissipation and High

Efficiency. It is a SMD type LED which can be used

in various applications.



## **Recommended Solder Pattern**

(Suggest Stencil t=0.12 mm)

#### RECOMMENDED STENCIL PATTERN (HATCHED AREA IS OPENING)

#### RECOMMENDED PCB SOLDER PAD

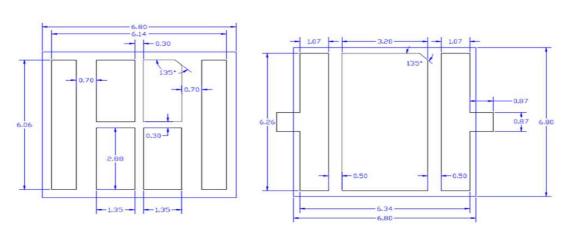
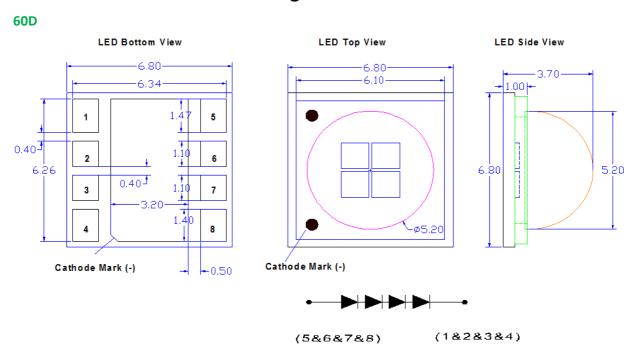


Figure 1. IN-C68QABTM / IN-C68QACTM Recommended Solder Pattern

- \* All dimensions are in millimeters.
- \* Tolerance is ±0.13mm unless other specified.



## **Package Dimensions**



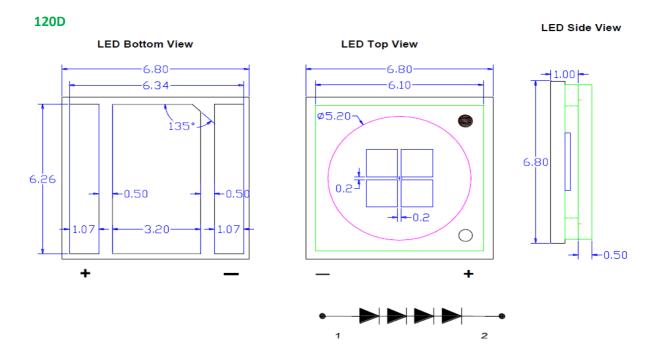


Figure 2. IN-C68QABTM / IN-C68QACTM Package Dimension

#### Note:

All dimensions are in millimeters.

Tolerance is ±0.13mm unless other specified.



Absolute Maximum Rating at 25°C

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current <sup>1</sup>	I <sub>F</sub>		500	1000	mA
Pulse Current (@1/10 duty) <sup>2</sup>	I <sub>P</sub>			1200	mA
Forward Voltage	$V_{F}$	12.0	14.0	16.8	V
Reverse Voltage	$V_{R}$		-20		V
Leakage Current (5V)	I <sub>R</sub>			10	μΑ
Junction Temperature <sup>3</sup>	Tj		85		$^{\circ}\!\mathbb{C}$
Operating Temperature Range	$T_{opr}$	-40	-	80	$^{\circ}\!\mathbb{C}$
Storage Temperature Range	$T_{stg}$	-40		80	$^{\circ}\!\mathbb{C}$
Soldering Temperature	$T_{sol}$			260	$^{\circ}\!\mathbb{C}$
Thermal Resistance Junction / Solder Point	R <sub>th</sub>		2.0		°C/W
Viewing Angle⁴	2θ <sub>1/2</sub>		60/120		Deg
Electrostatic Discharge (HBM)	ESD		8		KV

#### Notes:

- 1. When operating at other than ambient temperature, maximum allowable current depends on derating curves.
- 2. Pulse width = 0.01s & duty factor = 1/10.
- 3. When operating at maximum allowable current, Tj must be below 85  $^{\circ}$ C.
- 4. Viewing angle tolerance is ± 10°.

## Electrical Characteristics $T_A = 25\mathbb{C}$ (Note 1)

	V <sub>F</sub> (V)@700mA			Viewing Angle	I <sub>R</sub> (μA)@V <sub>R</sub> =5V
Product	min	typ	max	<b>2</b> θ 1/2	max
IN-C68QABTM UV Series IN-C68QACTM UV Series	12.0		16.8	60/120	10

#### Notes:

1. Performance guaranteed only under conditions listed in above tables.

#### **ESD Precaution**

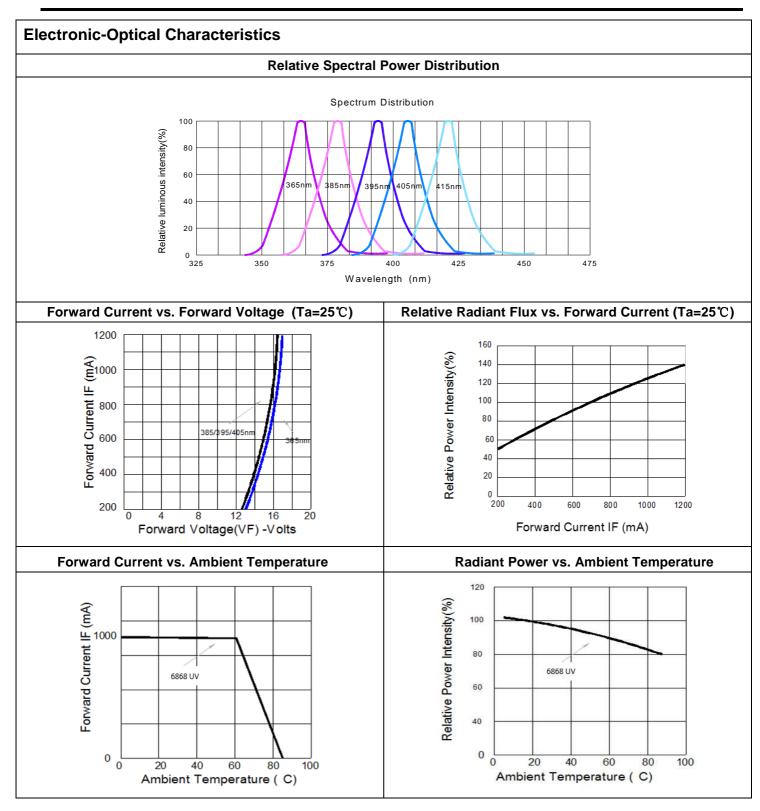
ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).



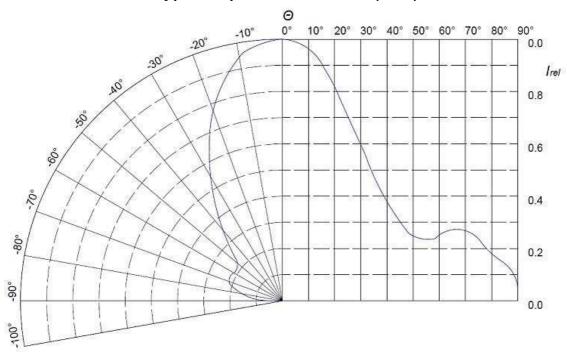


#### Notes:

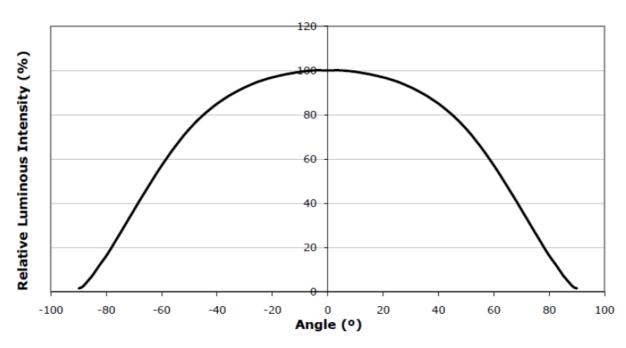
Viewing angle( $2\theta 1/2$ ) ±  $10^{\circ}$ 



## Typical Spatial Distribution(60D)



# Typical Spatial Distribution(120D)



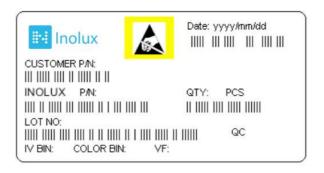


## **Ordering Information**

Product	Emission Color	Viewing Angle	Orderable Part Number
	U2:365~370nm	60°	IN-C68QABTMU2
	02.303 3701111	120°	IN-C68QACTMU2
	U4:380~390nm U5:390~400nm	60°	IN-C68QABTMU4
IN-C68QA(X)TM		120°	IN-C68QACTMU4
		60°	IN-C68QABTMU5
		120°	IN-C68QACTMU5



## **Label Specifications**



## **Inolux P/N:**

I	N	-	С	6	8	Q	Α	Х	Т	М		Х	-	Χ	Х	Χ	Х
			Material	Pac	kage	Die Qty.	Circuit	View Angle	Orientation	Current	Lens	Color			Custoi Stam		
	olux ИD		C = Ceramic Type	• Q • A	: 4 ch : 4 se iew A B: 6	ips ries	.8 x 6.8 mr	n	T = Top Mount	M = 700mA	(Blank) = Clear	U2 = 365-370nm U4 = 380-390nm U5 = 390-400nm					

## Lot No.:

Z	2	0	1	7	01	24	001
Internal		Year (2017	, 2018,)		Month	Date	Serial
Tracker		1Cai (2017	, 2010,		Wionth	Date	Scriai



# **Peak Wavelength Binning**

Peak Wavelength unit: nm@700mA									
Bir	n Code	Min	Max						
U2	R1	365	370						
U4	SA	380	385						
04	SB	385	390						
U5	TA	390	395						
05	ТВ	395	400						

#### Notes:

- 1. Binning current is 700mA
- 2. Wavelength tolerance ± 2nm

## **Voltage Binning**

	Volta	ge unit: V@700mA	
Peak Wavelength	Bin Code	Min	Max
	CO	12.0	12.8
	C1	12.8	13.6
U2: 365~400nm	C2	13.6	14.4
02. 365 400mm	C3	14.4	15.2
	C4	15.2	16.0
	C5	16.0	16.8

- 1. Binning current is 700mA
- 2. Voltage tolerance ± 0.8V



# Radiant flux (Power) binning

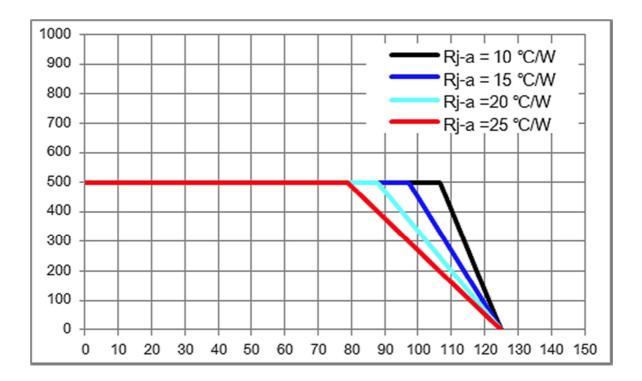
	Radiant flux (Power) unit: mw@700mA				
Peak Wavelength	Bin Code Min Max				
	P35	3,000	3,500		
U2. 265~270mm	P40	3,500	4,000		
U2: 365~370nm	P45	4,000	4,500		
	P50	4,500	5,000		
	P50	4,500	5,000		
114. 200~200mm	P55	5,000	5,500		
U4: 380~390nm	P60	5,500	6,000		
	P65	6,000	6,500		
	P50	4,500	5,000		
UE: 200×400 mm	P55	5,000	5,500		
U5: 390~400nm	P60	5,500	6,000		
	P65	6,000	6,500		

- 1. Tolerance of Forward voltage (VF) ±0.8V
- 2. Tolerance of Radiometric Power (Po) ±10%
- 3. Tolerance of Wavelength ±2nm



## **Thermal Design**

Thermal design of the end product is important. The thermal resistance between the junction and the solder point (ROJ-S) and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (Rja) by the following equation.

Tj = Ta + Rja\*W

Tj = LED junction temperature

Ta = Ambient temperature

Rja= Thermal resistance between the junction and ambient

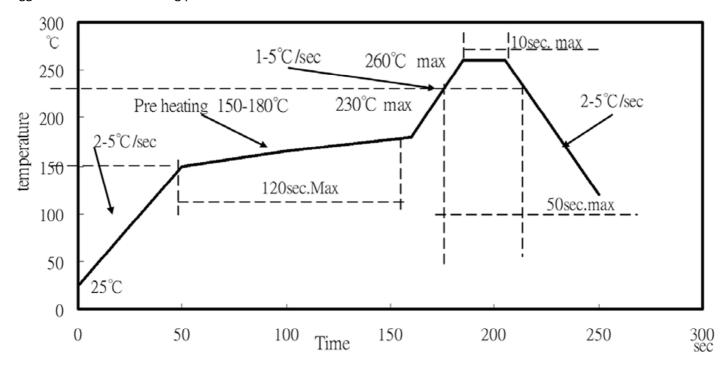
 $W = Input power (I_F*V_F)$ 



## **Reflow Soldering**

The LEDs can be soldered using the parameter listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is preferred for the LEDs.

Suggested lead-free soldering profile:

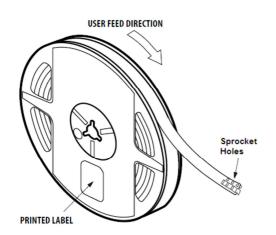


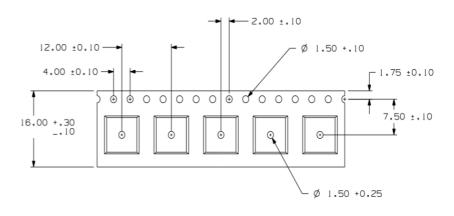
- 1. The recommended reflow temperature is 240°C(±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not stress the silicone resin while it is exposed to high temperature.
- 3. The number of reflow process should not exceed 3 times.



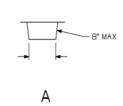
## **Packing**

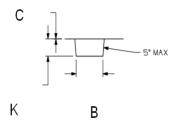
The carrier tape conforms to EIA-481D.

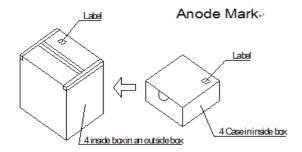




Item	Dimension	Tolerance	Unit
Α	7.35	±0.10	mm
В	B 7.25		mm
С	0.33	±0.02	mm
D 4.35		±0.10	mm







- 1. Each Reel (minimum number of pieces is 100 and maximum is 350 packed in a moisture-proof bag along with 2 packs of desiccant and a humidity indicator card.
- 2. A maximum of 5 moisture-proof bags are packed in an inner box (size: 240mm x 200mm x 105mm  $\pm$  5mm).
- 3. A maximum of 4 inner boxes are put in an outer box (size: 410mm x 255mm x 230mm  $\pm 5$ mm).
- 4. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.

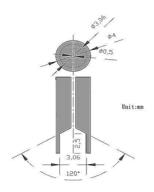


### **Precautions**

- 1. Recommendation for using LEDs
  - 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
  - 1.2 Avoid mechanical stress on LED lens.
  - 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
  - 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging.

#### 2. Pick & place nozzle

The pickup tool was recommended and shown as below:



### 3. Lens handling

Please follow the guideline to pick LEDs:

- 3.1 Use tweezers to pick LEDs.
- 3.2 Do not touch the lens by using tweezers.
- 3.3 Do not touch lens with fingers.
- 3.4 Do not apply more than 4N of force (400g) directly onto the lens.

#### 4. Lens cleaning

In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

- 4.1 Try gently wiping with a dust-free cloth.
- 4.2 If needed, use a dust-free cloth and isopropyl alcohol to gently remove the dirt from the lens surface.
- 4.3 Do not use other solvents as they may react with the LED assembly.
- 4.4 Do not use ultrasonic cleaning which will damage the LEDs.



# **Test Items and Results of Reliability**

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	-40°C 30min ↑↓5min 125 °C 30min	100 cycles	0/22	AECQ101
High Temperature Storage	Ta=100°C	1000 hrs	0/22	EIAJ ED-4701 200 201
Humidity Heat Storage	Ta=85℃ RH=85%	1000 hrs	0/22	EIAJ ED-4701 100 103
Low Temperature Storage	Ta=-40°C	1000 hrs	0/22	EIAJ ED-4701 200 202
Life Test	Ta=25℃ lf=500mA	1000 hrs	0/22	Tested with IN standard
High Humidity Heat Life Test	85°C RH=85% If=500mA	1000 hrs	0/22	Tested with IN standard
High Temperature Life Test	Ta=85°C	1000 hrs	0/22	Tested with IN standard
ESD(HBM)	8KV at 1.5kΩ;100pf	3 Times	0/22	MIL-STD-883

Criteria for Judging the Damage								
lk a ma	Curre le o l	Condition Criteria for Judg	Criteria for Judgment					
Item	Symbol		Max					
Forward Voltage	VF	lf=500mA	LSL ×0.9	USL ×1.1				
Reverse Current	IR	VR =5V	-	100μΑ				
Luminous Intensity	lv	lf=500mA	LSL ×0.7	USL ×1.2				

#### Notes:

1. USL: Upper specification level

2. LSL: Lower specification level





**Revision History** 

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	06-28-2018

### **DISCLAIMER**

INOLUX reserves the right to make changes without further notice to any products herein to improve reliability, function or design. INOLUX does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

### LIFE SUPPORT POLICY

INOLUX's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of INOLUX or INOLUX CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for High Power LEDs - Single Colour category:

Click to view products by Inolux manufacturer:

Other Similar products are found below: